

N-Channel 100-V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | |
|---------------------|---------------------------------|---------------------------------|-----------------------|--|--|--|
| V _{DS} (V) | $R_{DS(on)}\left(\Omega\right)$ | I _D (A) ^d | Q _g (Typ.) | | | |
| 100 | 0.063 at V _{GS} = 10 V | 6.8 | 9 nC | | | |
| 100 | 0.084 at V _{GS} = 6 V | 5.8 | 3110 | | | |

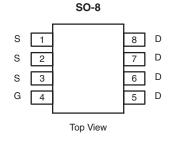
FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested

RoHS COMPLIANT HALOGEN FREE

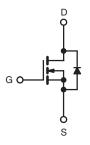
APPLICATIONS

- High Frequency Boost Converter
- LED Backlight for LCD TV



Ordering Information: Si4100DY-T1-E3 (Lead (Pb)-free)

Si4100DY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

| Parameter | Symbol | Limit | Unit | | |
|--|-----------------------------------|-----------------|---------------------|----|--|
| Drain-Source Voltage | V _{DS} | 100 | V | | |
| Gate-Source Voltage | | V_{GS} | ± 20 | V | |
| | T _C = 25 °C | | 6.8 | | |
| Continuous Drain Current (T = 150 °C) | T _C = 70 °C | | 5.4 | | |
| Continuous Drain Current (T _J = 150 °C) | T _A = 25 °C | l _D | 4.4 ^{a, b} | | |
| | T _A = 70 °C | | 3.5 ^{a, b} | ^ | |
| Pulsed Drain Current | I _{DM} | 20 | A | | |
| Continuous Source-Drain Diode Current | T _C = 25 °C | 1. | 5 | | |
| | T _A = 25 °C | ls – | 2.1 ^{a, b} | | |
| Single Avalanche Current | L = 0.1 mH | I _{AS} | 19 | | |
| Single Avalanche Energy | | E _{AS} | 18 | mJ | |
| | T _C = 25 °C | | 6 | | |
| Maximum Dawar Dissination | T _C = 70 °C | P _D | 3.8 | w | |
| Maximum Power Dissipation | T _A = 25 °C | | 2.5 ^{a, b} | VV | |
| | T _A = 70 °C | | 1.6 ^{a, b} | | |
| Operating Junction and Storage Temperature | T _J , T _{stg} | - 55 to 150 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | | |
|---|--------------|------------|---------|------|-------|--|--|
| Parameter | Symbol | Typical | Maximum | Unit | | | |
| Maximum Junction-to-Ambient ^{b, c} | t ≤ 10 s | R_{thJA} | 37 | 50 | °C/W | | |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 17 | 21 | O/ VV | | |

Notes

- a. Surface Mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 85 °C/W.
- d. $T_C = 25$ °C.

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| Parameter | Symbol | Test Conditions | Min. | Тур. | Max. | Unit | |
|---|-------------------------|---|------|-------|-------|-----------|--|
| Static | | | l | | 1 | | |
| Drain-Source Breakdown Voltage | V _{DS} | $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$ | 100 | | | V | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | J 050A | | 120 | | mV/°C | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = 250 μA | | - 9 | | | |
| Gate-Source Threshold Voltage | V _{GS(th)} | $V_{DS} = V_{GS}$, $I_D = 250 \mu A$ | 2 | | 4.5 | V | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$ | | | ± 100 | nA | |
| | I _{DSS} | V _{DS} = 100 V, V _{GS} = 0 V | 1 10 | | 1 | μΑ | |
| Zero Gate Voltage Drain Current | | V _{DS} = 100 V, V _{GS} = 0 V, T _J = 55 °C | | | 10 | | |
| On-State Drain Current ^a | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$ | 20 | | | Α | |
| _ | 5 | $V_{GS} = 10 \text{ V}, I_D = 4.4 \text{ A}$ | | 0.051 | 0.063 | | |
| Drain-Source On-State Resistance ^a | R _{DS(on)} | $V_{GS} = 6 \text{ V}, I_D = 3.8 \text{ A}$ | | 0.069 | 0.084 | Ω | |
| Forward Transconductance ^a | 9 _{fs} | V _{DS} = 15 V, I _D = 4.4 A | | 10 | | S | |
| Dynamic ^b | | | | | l | | |
| Input Capacitance | C _{iss} | | | 600 | | | |
| Output Capacitance | C _{oss} | $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | | 90 | | pF | |
| Reverse Transfer Capacitance | C _{rss} | | | 50 | | | |
| Total Gate Charge | Q _g | $V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 4.4 \text{ A}$ | | 13.5 | 20 | | |
| | | | | 9 | 13.5 | nC | |
| Gate-Source Charge | Q_{gs} | $V_{DS} = 50 \text{ V}, V_{GS} = 6 \text{ V}, I_{D} = 4.4 \text{ A}$ | | 3 | | | |
| Gate-Drain Charge | Q_{gd} | | | 4.6 | | | |
| Gate Resistance | R_g | f = 1 MHz | | 1 | | Ω | |
| Turn-On Delay Time | t _{d(on)} | | | 15 | 25 | | |
| Rise Time | t _r | V_{DD} = 50 V, R_L = 14.3 Ω | | 12 | 20 | | |
| Turn-Off Delay Time | t _{d(off)} | $\text{I}_\text{D}\cong 3.5~\text{A},~\text{V}_\text{GEN}=6~\text{V},~\text{R}_g=1~\Omega$ | | 12 | 20 | | |
| Fall Time | t _f | | | 10 | 15 | | |
| Turn-On Delay Time | t _{d(on)} | | | 10 | 15 | - ns - | |
| Rise Time | t _r | V_{DD} = 50 V, R_L = 14.3 Ω | | 12 | 20 | | |
| Turn-Off Delay Time | t _{d(off)} | $I_D\cong 3.5$ A, V_{GEN} = 10 V, R_g = 1 Ω | | 15 | 25 | | |
| Fall Time | t _f | | | 10 | 15 | | |
| Drain-Source Body Diode Characteristi | cs | | | | • | | |
| Continuous Source-Drain Diode Current | I _S | $T_C = 25 ^{\circ}C$ | | | 5 | ۸ | |
| Pulse Diode Forward Current | I _{SM} | | | | 20 | A | |
| Body Diode Voltage | V_{SD} | I _S = 3.5 A, V _{GS} = 0 V | | 0.8 | 1.2 | V | |
| Body Diode Reverse Recovery Time | t _{rr} | | | 45 | 70 | ns | |
| Body Diode Reverse Recovery Charge | Q _{rr} | I _F = 3.5 A, dI/dt = 100 A/μs, T _J = 25 °C | | 80 | 120 | nC | |
| Reverse Recovery Fall Time | ta | $I_F = 3.3 \text{ A}, \text{ ul/ul} = 100 \text{ A/}\mu\text{s}, I_J = 25 ^{\circ}\text{C}$ | | 33 | | ns | |
| Reverse Recovery Rise Time | t _b | | | 12 | | | |

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing.

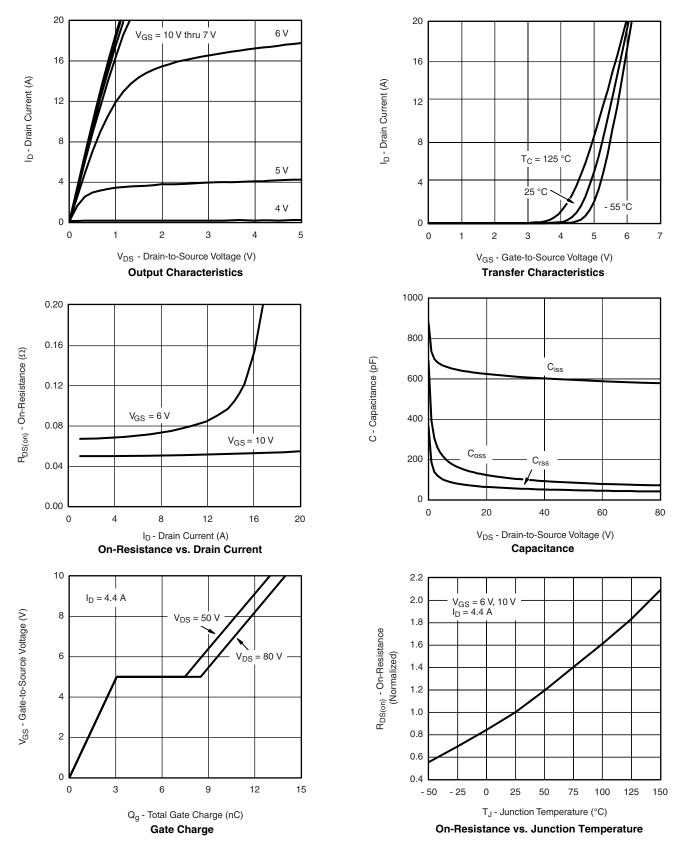
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





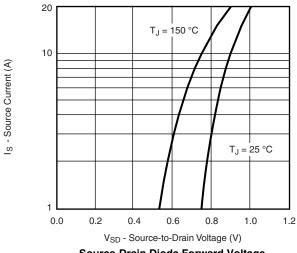


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

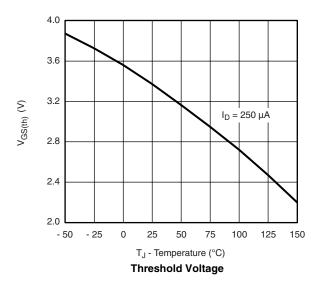


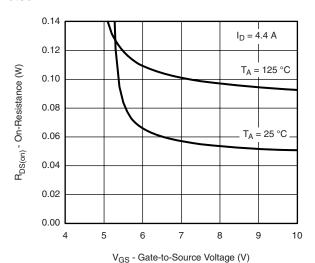
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

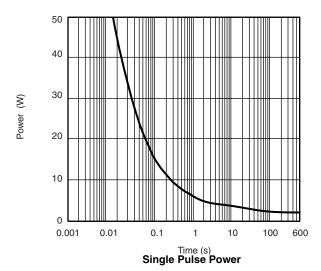


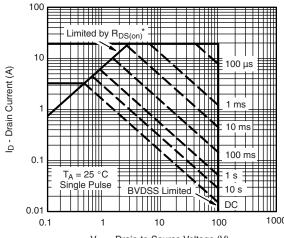
Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage





V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

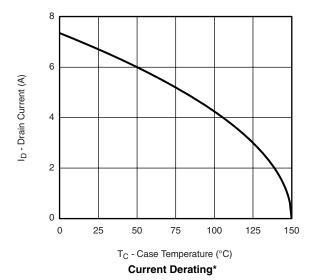
Safe Operating Area, Junction-to-Ambient

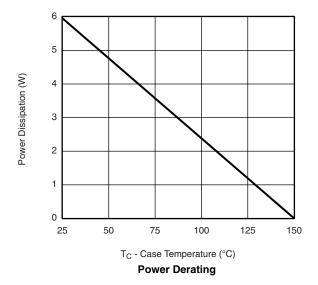






TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



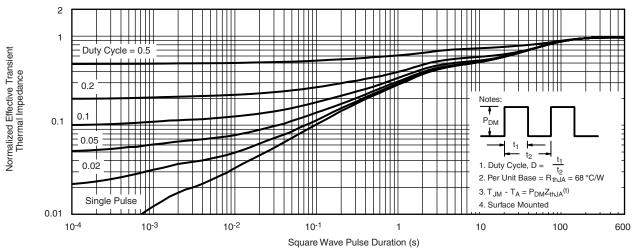


^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

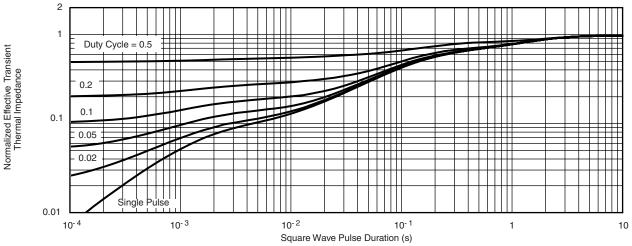
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







| | MILLIMETERS INCHES | | | HES | | |
|--------------------------------|--------------------|----------|--------|-----------|--|--|
| DIM | Min | Max | Min | Max | | |
| Α | 1.35 | 1.75 | 0.053 | 0.069 | | |
| A ₁ | 0.10 | 0.20 | 0.004 | 0.008 | | |
| В | 0.35 | 0.51 | 0.014 | 0.020 | | |
| С | 0.19 | 0.25 | 0.0075 | 0.010 | | |
| D | 4.80 | 5.00 | 0.189 | 0.196 | | |
| Е | 3.80 | 4.00 | 0.150 | 0.157 | | |
| е | 1.27 | 1.27 BSC | | 0.050 BSC | | |
| Н | 5.80 | 6.20 | 0.228 | 0.244 | | |
| h | 0.25 | 0.50 | 0.010 | 0.020 | | |
| L | 0.50 | 0.93 | 0.020 | 0.037 | | |
| q | 0° | 8° | 0° | 8° | | |
| S | 0.44 | 0.64 | 0.018 | 0.026 | | |
| ECN: C-06527-Rev. I. 11-Sep-06 | | | | | | |

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LON NOTE



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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